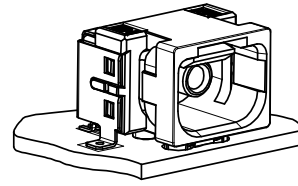
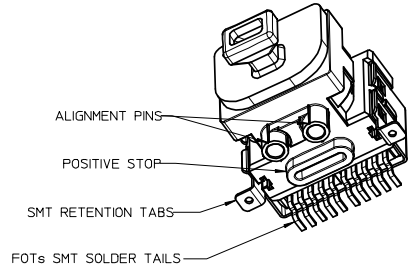
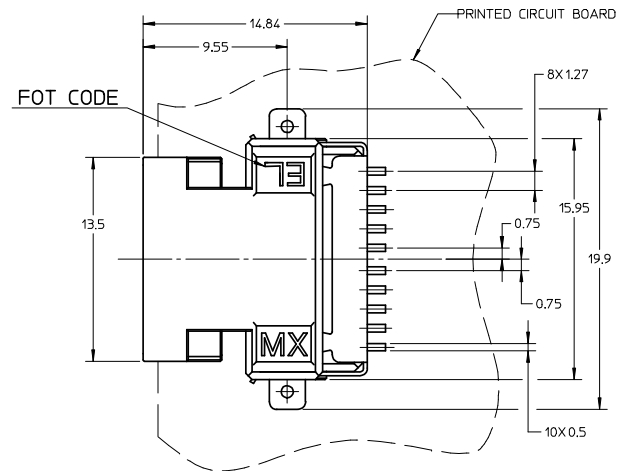


SMI/SMT TRANSCEIVER ASSEMBLY P/N	FOT's TYPE	FOT CODE
1061082200	IEEE-1394/ DIGITAL FDL300K	IE
1061083200	10/100 ETHERNET EDL300K	EL
1061084200	INDUSTRIAL DATA LINK IDL300K	ID

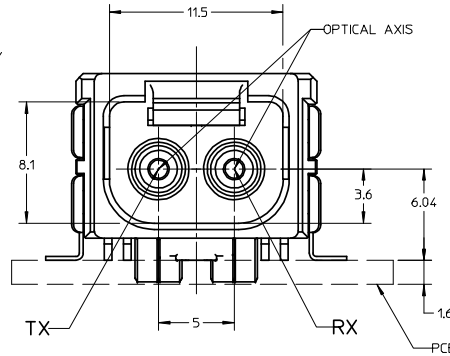
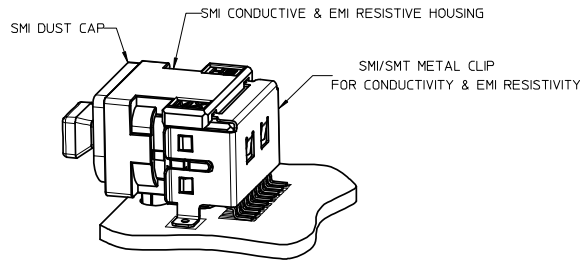


DUST CAP NOT SHOWN

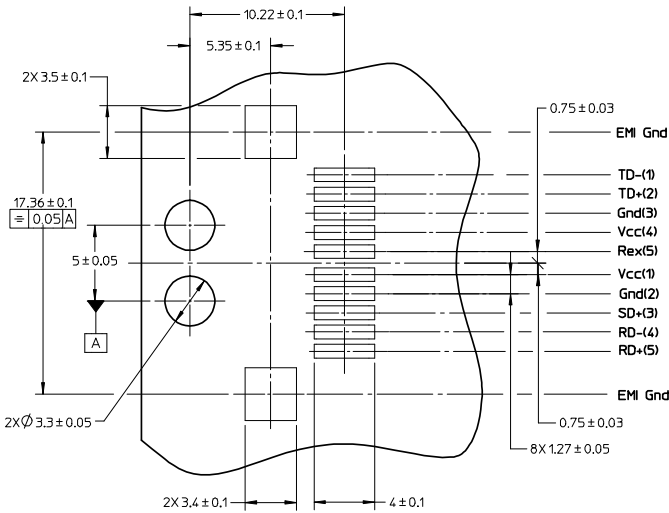
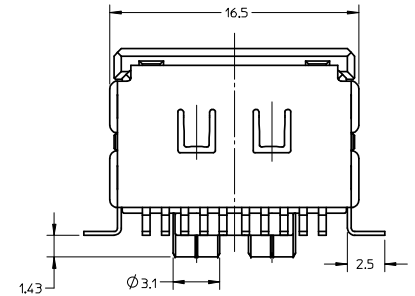
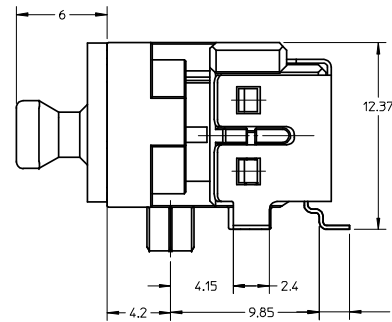
ISOMETRIC VIEWS  
SCALE 2.5:1



DUST CAP NOT SHOWN



SMI TRANSCEIVER ASSEMBLY  
MOUNTED ON THE PCB  
DUST CAP NOT SHOWN



RECOMMENDED PCB LAYOUT

NOTE:  
1. ALL DIMENSIONS ARE FOR REFERENCE ONLY EXCEPT FOR RECOMMENDED PCB LAYOUT.  
2. ATTACHMENT OF THE COMPONENT TO THE PCB SHALL BE VIA HOT BAR, LASER OR IR SOLDERING.  
RE-FLOW OVEN SOLDERING IS NOT APPROVED AT THIS TIME.

<b>ENTER DESCRIPTION</b> EC NO: MF2008-0555 DRWN:SMIGO 2008/06/11 CHKD: 2008/06/11 APPR:SMIGO 2008/06/26	<b>QUALITY SYMBOLS</b> 	<b>GENERAL TOLERANCES (UNLESS SPECIFIED)</b>		<b>DIMENSION STYLE</b> MM ONLY	<b>SCALE</b> 4:1	<b>DESIGN UNITS</b> METRIC	<b>THIRD ANGLE PROJECTION</b>
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± --- ± --- 1 PLACE ± --- ± ---	mmm INCH ± --- ± --- ± --- ± --- ± --- ± ---	<b>DRAWN BY</b> BG 09/12/06	<b>DATE</b> 09/12/06	<b>TITLE</b> SMI TRANSCEIVER ASSEMBLY SURFACE MOUNT SOLDERING	
<b>REV</b> B	<b>DESCRIPTION</b> DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	<b>APPROVED BY</b> SE 9/15/06		<b>MATERIAL NO.</b> SEE TABLE	<b>DOCUMENT NO.</b> SD-106108-X200	<b>SHEET NO.</b> 1 OF 1	
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					